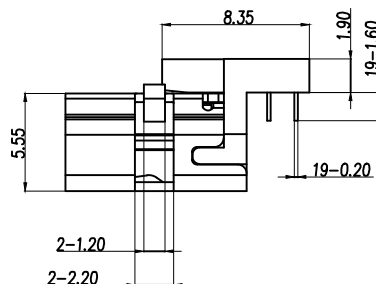
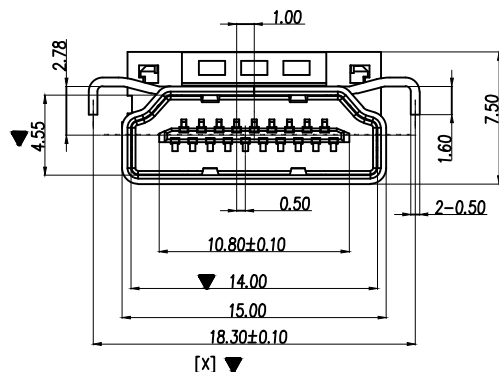


GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2013/2/20	Jamie Zie
A1			Initial	2013/2/26	Jamie Zie



- 1, CONTACT: PHOSPHOR BRONZE T0.20mm;
CONTACT PLATING: GOLD FLASH ON CONTACT AREA, MISTY GRAY Sn 80u" Min
ON SOLDER TAIL, 50u" NICKEL PLATING OVER ALL.
- 2, SHELL: BRASS T0.50mm;
SHELL PLATING: SOLDERABLE NICKEL 50u" MIN.
- 3, HOUSING & KEY: LCP UL94V-0 BK HF.

ELECTRICAL CHARACTERISTICS:

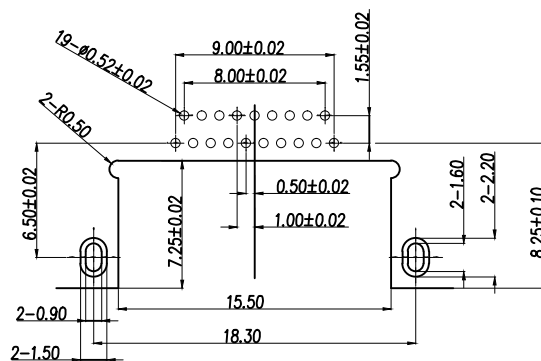
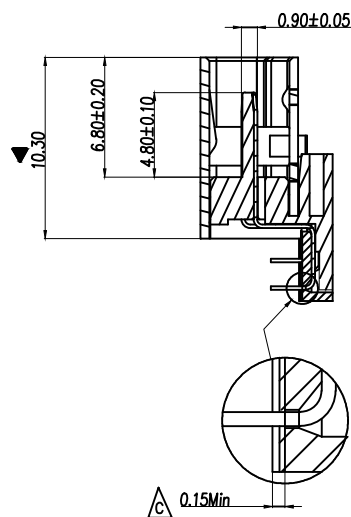
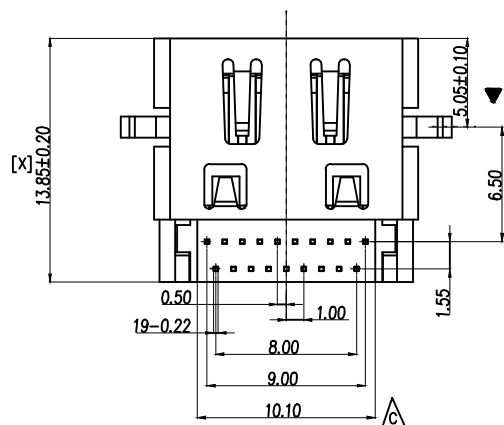
- 1, CONTACT CURRENT PATING: 0.8A MAX; RATED VOLTAGE: 40V AC;
2, CONTACT RESISTANCE: INITIAL 40m ohms MAX,
AFTER TEST CHANGE FROM INITIAL VALUE 30m ohms MAX.
3, SHELL RESISTANCE: INITIAL 50m ohms MAX,
AFTER TEST CHANGE FROM INITIAL VALUE 50m ohms MAX.
4, DIELECTRIC WITHSTANDING VOLTAGE: 500V AC RMS.
5, INSULATION RESISTANCE: UNMATED PLUG: 100M ohms MIN, AT 500V DC;
MATED PLUG: 10M ohms MIN, AT 150V DC;

MECHANICAL CHARACTERISTICS:

- 1, CONNECTOR MATING FORCE: 4.5kgf MAX;
2, CONNECTOR UNMATING FORCE: INITIAL 1.0~4.0kgf; AFTER LIFE CYCLING TEST: 0.5~4.0kgf.
3, DURABILITY: 5000 CYCLES.
4, OPERATING TEMPERATURE RANGE: -40~+85°C; HUMIDITY: 85%RH MAX.

▼ DENOTES MAJOR DIMENSION MEASUREMENT REQUIRE.

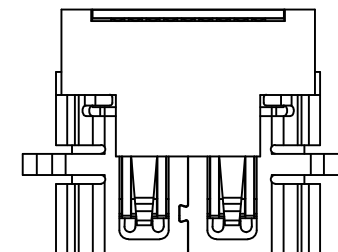
[X] IS CPK DIMENSION.



RECOMMENDED PCB LAYOUT T=1.0±0.05
COMPONENT SIDE (TOL: ±0.05)

MATRIX PART NO:

MHD X - X XX XX - XXX - XX
F: FEMALE
M: MALE
A: Non case
B: C2680
C: 5191
D: SPCC
Pin Number
Series
Planting
00: Gold Flash
15: 15u"
30: 30u"
RS: RoHs
HF: Halogen Free



NO	VARIETY	QTY	MATERIAL	REMARK
 Matrix Electronics Co., Ltd				
TOLERANCE: X.X ±0.38 X.XX ±0.25 X.XXX ±0.13 ANGLE: ±3°		DESIGN BY : Jamie Zie	DATE : 2013/2/26	PART NAME: HDMI AF G/F CONN
UNIT: mm [inch]		CHECKED BY: David Chou	DATE : 2013/2/26	PART NO. MHDF-B1901-025-RS
SCALE: 1:1		APPROVED BY1: Richard Hsieh	DATE : 2013/2/26	MOLD NO. NA
SIZE: A4		APPROVED BY2: Richard Hsieh	DATE : 2013/2/26	DRAW NO. SHEET NO. 1 OF 1